

## DATA ITEM DESCRIPTION

**Title:** Customized Microelectronics Devices Source Protection Plan

**Number:** DI-MGMT-81763

**Approval Date:** 09 Feb 2009

**AMSC Number:** 9057

**Limitation:** N/A

**DTIC Applicable:** No

**GIDEP Applicable:** No

**Office of Primary Responsibility:** NS/T54

**Applicable Forms:** N/A

### Use/Relationship:

The Customized Microelectronics Devices Source Protection Plan documents the approved integrated strategy for supplying trust and managing risk in the supply chain management for customized microelectronics devices, e.g. Application Specific Integrated Circuit (ASICs) that are used in Government systems. Trustedness derives from supply chain compliance with mission assurance guidance in DoDI 8500.2, Information Assurance Implementation, Enclosure E3.3, such that the confidentiality, availability and integrity of national security critical components are sufficiently robust to perform their missions successfully in the operational environments for which they were designed.

This Data Item Description (DID) is applicable to all customized microelectronics devices designated to be used in any Government (civilian or military) systems or equipment.

This DID contains the format and content preparation instructions for the data product generated by the specific and discrete task requirement as delineated in either the contract, Memorandum of Understanding (MOU), Memorandum of Agreement (MOA) or User Partnership Agreement (UPA) and paragraph 2 of NSA/CSS Policy 3-8, Integration of Customized Microelectronics Products and Services.

### Requirements:

1. Reference Documents: The applicable issue of the documents cited herein, including approval dates and dates of any applicable amendments, notices, and revisions, shall be cited in the current issue of the DODISS at the time of the solicitation, and for non-DODISS-listed documents, as stated herein. The following document is available from National Security Agency, 9800 Savage Rd., Suite 6538, Fort George G. Meade, Md. 20755-6538; Attn: T54: NSA/CSS Policy 3-8, Integration of Customized Microelectronics Products and Services.
2. Format. The Plan shall be in contractor format on 8½ x 11” (metric size A4) paper. Abbreviations and acronyms shall be defined when first used in the text and shall be placed in a glossary.
3. Content: The Plan shall be in accordance with NSA/CSS Policy 3-8, paragraph 2 and shall include the following information:

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3.1 Cover/Title Page. The following information shall appear on the cover and title page:

- a. Plan title.
- b. Date of issue.
- c. Report number/revision number or letter.
- d. Contract Number (if applicable) or reference to the applicable MOU or MOA or UPA.
- e. Vendor name and address.
- f. Program title, including program name.
- g. Security classification, if classified.

3.2 Revision Control Page. The revision control page shall list the following information:

- a. Each revision number or letter.
- b. Date of each revision.
- c. Pages affected by each revision.

3.3 Table of Contents. The Table of Contents shall identify the following:

- a. The title of the starting page of each major section and paragraph of the report.
- b. The page, identifying number and title of each drawing, illustration, figure and table.

3.4 Chapters. The report shall contain the following sections of information:

- a. General Information. The Plan identifies a complete list of all accredited trusted vendors under consideration for the procurement, development, production, assembly and test of customized microelectronics devices. In addition, where a trusted supplier is not identified, the Plan addresses the specific risk mitigation strategy for that area.
- b. A brief functional description that defines the criticalness of the customized microelectronics product under development.
- c. In each of the following manufacturing process areas, identify the trusted accredited vendor, to include the supplier of the parts procured:
  - (1) Design
  - (2) Mask-making
  - (3) Fabrication
  - (4) Assembly
  - (5) Test
  - (6) Reliability
  - (7) Failure Analysis
  - (8) Other Microelectronics Manufacturing Processes
- d. The list shall include the trusted vendor, and the classification and handling procedures that apply for each area. For accredited trusted vendor information, visit website: [www.tapoffice.org](http://www.tapoffice.org). If a trusted accredited vendor cannot be identified to support an area, the Plan shall identify the vendor that is being considered and what approved risk mitigations are being applied to ensure trust and mission assurance.

4. END of DI-MGMT-81763